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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/721,260	11/26/2003	Toyokazu Sakata	TAI 145	6433	
23995 7:	590 07/20/2005		EXAMINER		
RABIN & Berdo, PC			VINH, LAN		
1101 14TH STREET, NW SUITE 500			ART UNIT	PAPER NUMBER	
WASHINGTON, DC 20005			1765	-	
			DATE MAILED: 07/20/200:	ς	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)				
		10/721,260	SAKATA, TOYOKA	NZU			
	Office Action Summary	Examiner	Art Unit				
	•	Lan Vinh	1765				
Period fo	The MAILING DATE of this communication or Reply	appears on the cover sheet v	with the correspondence add	iress			
THE - Exte after - If the - If NC - Failt Any	ORTENED STATUTORY PERIOD FOR RE MAILING DATE OF THIS COMMUNICATIOnsions of time may be available under the provisions of 37 CFF SIX (6) MONTHS from the mailing date of this communication e period for reply specified above is less than thirty (30) days, a period for reply is specified above, the maximum statutory per to reply within the set or extended period for reply will, by streply received by the Office later than three months after the med patent term adjustment. See 37 CFR 1.704(b).	N. R 1.136(a). In no event, however, may a reply within the statutory minimum of th riod will apply and will expire SIX (6) MC atute, cause the application to become A	a reply be timely filed irty (30) days will be considered timely. NTHS from the mailing date of this cor ABANDONED (35 U.S.C. § 133).	mmunication.			
Status	•						
1)[🛛	Responsive to communication(s) filed on 2	6 November 2003.					
2a)□	This action is FINAL . 2b)⊠ 1	his action is non-final.					
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is							
	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.						
Disposit	ion of Claims			_			
5)□	Claim(s) 1-15 is/are pending in the applicated 4a) Of the above claim(s) is/are with Claim(s) is/are allowed. Claim(s) 1-15 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and	drawn from consideration.					
Applicati	ion Papers						
9)	The specification is objected to by the Exam	niner.					
10)	The drawing(s) filed on is/are: a)	accepted or b) objected to	by the Examiner.				
	Applicant may not request that any objection to	***	· ,				
11)	Replacement drawing sheet(s) including the cor The oath or declaration is objected to by the						
Priority ι	ınder 35 U.S.C. § 119						
12)⊠ a)[Acknowledgment is made of a claim for fore All b) Some * c) None of: 1. Certified copies of the priority docum 2. Certified copies of the priority docum 3. Copies of the certified copies of the papplication from the International Bur See the attached detailed Office action for a	ents have been received. ents have been received in a priority documents have been eau (PCT Rule 17.2(a)).	Application No n received in this National S	Stage			
Attachmen	t(s)						
	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948)		Summary (PTO-413) (s)/Mail Date				
3) 🛛 Inforr	e of Dransperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449 or PTO/SB/ r No(s)/Mail Date 112603.		Informal Patent Application (PTO-	152)			

the

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 1-9 are rejected under 35 U.S.C. 102(e) as being anticipated by Li et al (US 2003/0024902 A1)

Li discloses a method for etching low-k dielectric material. The method comprises the steps of:

plasma etching an interlayer insulating comprises low-k film 38 using a gas mixture including C4F8/fluorocarbon gas, oxygen and Ar (col 3, paragraph 0023, col 6, paragraph 0047, Table 4), and under a pressure of 60-200 mTorr and a RF power of 50-1000 Watts (col 5, paragraph 0034, 0035), which encompasses the claimed range of 600 Watts or less

The limitations of claims 2, 6 have been discussed above

Regarding claims 3, 7, Li discloses that the low-k dielectric film comprises SOG (col 3, paragraph 0025)

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Regarding claims 4, 9, Li discloses the ratio of oxygen to a combined fluorocarbon gas and oxygen is 5 sccm of oxygen:12 sccm of C4F8+5 sccm of oxygen (5 sccm/17 sccm or approximately 29%) (table 4)

Regarding claim 8, Li discloses forming an etch stop layer 36 above the low-k dielectric layer 38 (col 3, paragraph 0023)

3. Claims 10-15 are rejected under 35 U.S.C. 102(e) as being anticipated by Tsai et al (US 2003/0008511 A1)

Tsai discloses a method for forming a dual-damascene comprises the steps of: forming a first contact/interconnection 12 (col 2, paragraph 0036)

forming an interlayer low k dielectric layer 16 (SOG) on the contact 12 (col 4, paragraph 0041)

forming a contact hole 31 for electrically connecting the contact 12 and second metal/contact 34, in the layer 16 (fig. 6)

forming a trench/groove for embedding the second metal in the layer 16/interlayer dielectric layer (col 6, paragraph 0056, fig. 4)

plasma etching the contact hole using a gas mixture including C4F8, oxygen and argon gas under a pressure of 1.5 mTorr-10 Torr, which encompasses the claimed range of 60 mTorr or higher and RF power output of 500 Watts, which encompasses the claimed range of 600 Watts or less (col 6, paragraph 0055)

The limitations of claims 11-12 have been discussed above

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Regarding claims 13, Tsai discloses forming an etch stop layer 18 formed above the layer 16 (col 6, paragraph 0057)

Regarding claim 14, Tsai discloses the ratio of oxygen to a combined fluorocarbon gas and oxygen is 500 sccm of oxygen :500 sccm of C4F8+500 sccm of oxygen (500 sccm:1000 sccm or approximately 50%) (col 5, paragraph 0046)

Regarding claim 15, Tsai discloses plasma etching the contact hole and trench using a gas mixture including C4F8, oxygen and argon gas under a pressure of 1.5 mTorr-10 Torr, which encompasses the claimed range of 60 mTorr or higher and RF power output of 500 Watts, which encompasses the claimed range of 600 Watts or less (col 6, paragraph 0054, 0055)

Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lan Vinh whose telephone number is 571 272 1471. The examiner can normally be reached on M-F 8:30-5:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571 272 1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Business Center (EBC) at 866-217-9197 (toll-free).

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July 19, 2005